L Number	Hits	Search Text	DB	Time stamp
1	9171	257/\$.ccls. and (PCB or (printed adj circuit adj board))	USPAT;	2004/02/03 09:08
		·	EPO; JPO;	,
			DERWENT;	
			USOCR	
2	2801	(257/\$.ccls. and (PCB or (printed adj circuit adj	USPAT;	2004/02/03 09:08
		board))) and opening	EPO; JPO;	
		,	DERWENT;	
			USOCR	
3	3953	(257/\$.ccls. and (PCB or (printed adj circuit adj	USPAT;	2004/00/02 40-54
3	3933	board))) and (opening or cavity)		2004/02/03 10:54
		board))) and (opening or cavity)	EPO; JPO;	
			DERWENT;	
	505	//057/h and mad/DOD and that I'm to	USOCR	
4	505	((257/\$.ccls. and (PCB or (printed adj circuit adj	USPAT;	2004/02/03 09:20
		board))) and (opening or cavity)) and (conduct\$4 adj	EPO; JPO;	
		layers)	DERWENT;	
			USOCR	
5	77	( f ( (b and and an and	USPAT;	2004/02/03 09:18
		board))) and (isolat\$4 adj layer\$4)	EPO; JPO;	
			DERWENT;	
			USOCR	l
6	1614	(257/\$.ccls. and (PCB or (printed adj circuit adj	USPAT:	2004/02/03 09:18
		board))) and (insulat\$4 adj layer\$4)	EPO; JPO;	
			DERWENT;	
į			USOCR	
7	10	(257/\$.ccls. and (PCB or (printed adj circuit adj		2004/02/02 00:40
•	10		USPAT;	2004/02/03 09:18
		board))) and (isolation adj layer\$s)	EPO; JPO;	
İ			DERWENT;	
_	_	,,	USOCR	
8	3	(257/\$.ccls. and (PCB or (printed adj circuit adj	USPAT;	2004/02/03 09:18
		board))) and (isolating adj layer\$s)	EPO; JPO;	
1			DERWENT;	
			USOCR	
9	0	(257/\$.ccls. and (PCB or (printed adj circuit adj	USPAT;	2004/02/03 09:19
		board))) and (isolative adj layer\$s)	EPO; JPO;	
			DERWENT;	
			USOCR	
10	414	((257/\$.ccls. and (PCB or (printed adj circuit adj	USPAT;	2004/02/03 09:20
1		board))) and (insulat\$4 adj layer\$4)) and (conduct\$4	EPO; JPO;	200-1102100 05:20
:		adj layers)	DERWENT;	
		auj layers/	USOCR	
11	233	(((257/\$.ccls. and (PCB or (printed adj circuit adj		0004/00/02 00:00
''	200		USPAT;	2004/02/03 09:20
		board))) and (insulat\$4 adj layer\$4)) and (conduct\$4 adj layers)) and (opening or cavity)	EPO; JPO;	
		auj layers)) and (opening or cavity)	DERWENT;	
40	40~	///057/h 1 1 / DOD / 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	USOCR	
12	167	((((257/\$.ccls. and (PCB or (printed adj circuit adj	USPAT;	2004/02/03 09:31
		board))) and (insulat\$4 adj layer\$4)) and (conduct\$4	EPO; JPO;	1 .
		adj layers)) and (opening or cavity)) and wire	DERWENT;	
			USOCR	
13	209	(361/778).CCLS.	USPAT;	2004/02/03 10:22
			EPO; JPO;	
		·	DERWENT:	
			USOCR	
14	106	(361/789).CCLS.	USPAT;	2004/02/03 10:26
		(	EPO; JPO;	200-702100 10.20
-	,			
.			DERWENT;	
15	129	361/705 colo and multilavan	USOCR	0004/00/00 10 55
15	129	361/795.ccls. and multilayer	USPAT;	2004/02/03 10:29
			EPO; JPO;	4
			DERWENT;	
			USOCR	
16	186	361/795.ccls. and component	USPAT;	2004/02/03 10:33
			US-PGPUB;	
	Ì		EPO; JPO;	
1	1		DERWENT	1

17	14383	257/\$.ccls. and multilayer	USPAT;	2004/02/03 10:34
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
18	3772	(257/\$.ccls. and multilayer) and (isolate or isolative or	USPAT;	2004/02/03 10:34
		isolation or isolating)	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT	
19	2	(257/\$.ccls. and multilayer) and componet\$4	USPAT;	2004/02/03 10:35
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
20	6697	(257/\$.ccls. and multilayer) and component\$4	USPAT;	2004/02/03 10:35
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
21	3742	((257/\$.ccls. and multilayer) and component\$4) and	USPAT;	2004/02/03 10:54
		(bond or bonded or bonding)	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
22	884	(((257/\$.ccls. and multilayer) and component\$4) and	USPAT;	2004/02/03 10:36
		(bond or bonded or bonding)) and (diode or	US-PGPUB;	
		photodiode)	EPO; JPO;	
			DERWENT	
23	1245	((257/\$.ccls. and multilayer) and component\$4) and	USPAT;	2004/02/03 10:54
		(wire adj (bond or bonded or bonding))	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
24	579	(((257/\$.ccls. and multilayer) and component\$4) and	USPAT;	2004/02/03 10:55
		(wire adj (bond or bonded or bonding))) and (opening	EPO; JPO;	
		or cavity)	DERWENT;	
			USOCR	